Chip Module Production

Market-leading, innovative systems at affordable prices

The smart card market is characterised by strong competition and falling prices for components. This requires a higher level of automation and increased efficiency, without compromising quality and precision. Face these mounting challenges head-on with innovative machines and systems designed by ruhlamat to perform in the most demanding production environments.

Our affordable and industry-proven machine solutions provide the speed, quality and economy that will help you to sustain and maximise profitability in the future. We offer sophisticated, high-quality machines for the chip module production, ranging from encapsulation, testing and encoding of IC modules to glue tape lamination of module tapes.


Encapsulation is the method for protecting the chip and wires against mechanical stress and environmental influences. For this purpose, cast resin is dispensed and then cured by UV light or heat, depending on the type of resin.

The PowerSeal offers highest quality and maximum speed for the encapsulation of chip modules with up to 40,000 modules/hour.


The inspection of IC modules for smart cards and RFID devices, based on parametric and functional testing, is an integral part in the production flow and quality assurance.

The PowerTest is designed for high-speed testing and encoding of chip modules on 35 mm tapes. The system is also
perfectly suited for initialisation and personalisation of IC modules, including OS loading.

GTL700 - Glue Tape Lamination System [3]

The GTL700 is a highly reliable and flexible system for glue tape lamination of chip module tapes in preparation for the hot melt implanting process.

The very efficient system can operate stand-alone or inline, and is suitable for a wide range of IC module tapes (contact, contactless, and dual interface).


Links